



DEFENSE LOGISTICS AGENCY
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 COLUMBUS, OH 43216-5000

IN REPLY
 REFER TO

SEP 2 2003

DSCC-VQ (VQE-03-004657 /Mr. Johnson/614-692-0626/tj)

SUBJECT: Notification of Qualification, MIL-PRF-31032, CAGE Code 65337

Mr. Robert Hall
 Calumet Electronics Corp.
 25830 Depot Street
 Calumet, MI 49913-1985

Dear Mr. Hall:

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032 /1 & /2. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is August 29, 2003.

MANUFACTURER NAME & ADDRESS Calumet Electronics Corp. 25830 Depot Street Calumet MI 49913-1985	PLANT LOCATION Same	CAGE CODE: 65337 CONTACT: Mr. Robert Hall PHONE #: (906) 337-1305 FAX #: (906) 337-5359 EMAIL: rhall@cec-up.com WEBSITE: www.cec-up.com																										
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:		QUALIFICATION LETTER:																										
MIL-PRF-31032 /1 & /2 <table border="0"> <tr><td>Panel Size</td><td>18" X 24"</td></tr> <tr><td>Max. Board Thickness</td><td>0.125"</td></tr> <tr><td>Max/Min Hole Size</td><td>0.125" / 0.016"</td></tr> <tr><td>Aspect Ratio</td><td>8:01</td></tr> <tr><td>Max. Number of Layers</td><td>10</td></tr> <tr><td>Min. Conductor Width</td><td>0.006"</td></tr> <tr><td>Min. Conductor Spacing</td><td>0.003"</td></tr> <tr><td>Part Mounting</td><td>THM, SM</td></tr> <tr><td>Base Material</td><td>GF (Woven E-Glass, Epoxy resin)</td></tr> <tr><td>Finish System</td><td>Hot Air Solder Leveling (HASL)</td></tr> <tr><td></td><td>Au, Ni</td></tr> <tr><td>Hole Preparation</td><td>Chemical Etchpack</td></tr> <tr><td>Copper Plating</td><td>Electrodeposited Acid Copper</td></tr> </table>		Panel Size	18" X 24"	Max. Board Thickness	0.125"	Max/Min Hole Size	0.125" / 0.016"	Aspect Ratio	8:01	Max. Number of Layers	10	Min. Conductor Width	0.006"	Min. Conductor Spacing	0.003"	Part Mounting	THM, SM	Base Material	GF (Woven E-Glass, Epoxy resin)	Finish System	Hot Air Solder Leveling (HASL)		Au, Ni	Hole Preparation	Chemical Etchpack	Copper Plating	Electrodeposited Acid Copper	VQE-03-004657
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Test report number 31032-792-03 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during PCI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. This letter acts as a letter of delegation in accordance with Chapter 1.4.1 of DLAD 5000.4 and VI.C.1.c of DLAR 4120.13 for your local Government QAR to survey your facility listed above for compliance, as necessary.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Todd Johnson, (614) 692-0626.

Sincerely,



ROBERT P. EVANS
Chief
Sourcing and Qualifications Unit